

5 é / Descriptions

PDFN5 ~6 / x N ?ú 3 « | • ' ož

N-Channel MOSFET in a PDFN5 h 6 Plastic Package.

□ ª / Features

z Š U Â Ý ª ' z - C ô z z õ â > k U ë ½ , ä E z z ½ Š z —)í D }ož

Low $R_{DS(ON)}$ to minimize conductive loss; low Gate Charge for fast switching; Low Thermal resistance; HF Product.

Ð ÷ / Applications

P ' òož

Battery Management.

PIN1 Ã2 Ã3 Ö S

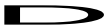
PIN4 ÖG

PIN5 Ã6 Ã7 Ã8 ÖD

, M V / Marking

• - ~ ª ¢ Ä

See Marking Instructions.

@ f Parameter	... Z Symbol	f > Rating	% y Unit
Drain-Source Voltage	V _{DS}		

BRCS015N04SZC

Ô ? d • Ž ¢ / Electrical Characteristic Curve

Ø □ =) ¢ / Package Dimensions

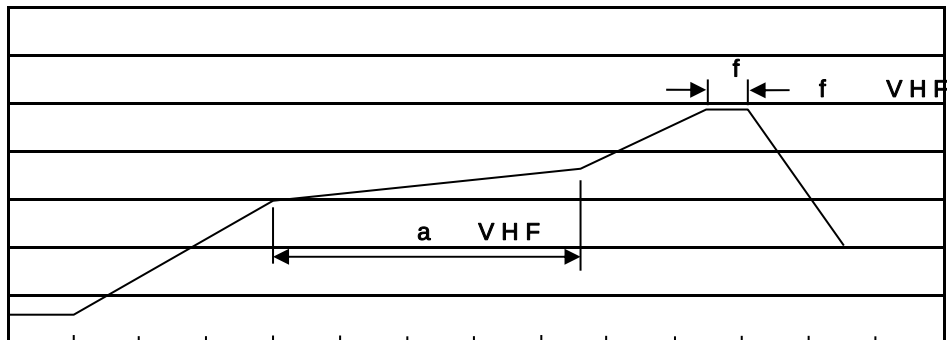
, M y f / Marking Instructions

BR
015N04S

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(8 y , [W A
015N04S y D } ° Z
 y Ÿ D Z W A k š Ÿ D Z J

Note y
BR y Company Code
015N04S y Product Type
****. Lot No. Code, code change with Lot No

Š WD t ... • Ž Ć (x /) / Temperature Profile for IR Reflow Soldering(Pb-Free)



^a Ć y

10• Ä ½ " † 150 ½ 180 - k ž • 60 ½ 90sec;

20• Q > " † 245 r 5 - k ž • 4 Ò 5 r 0.5sec;

30•D N ò i Ò 0 , † 2 ½ 10 - /sec.

Note:

1.Preheating:150~180 - , Time:60~90sec.

2.Peak Temp.:245 r 5 - , Duration:5 r 0.5sec.

3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

" † y 260 r 5 -

ž • y 10 r 1 sec.

Temp.:260±5

Time:10±1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type / x ¥ "	Units ;>û Ĥ					Dimension ;>û p . (unit /mm ³)		
	Units/Reel Q 2 &	Reels/Inner Box 2 & "	Units/Inner Box Q "	Inner Boxes/Outer Box " "	Units/Outer Box Q "	Reel	Inner Box	Outer Box
PDFN5 h 6	5000	2	10000	6	60000	13" h 12	360 h 360 h 50	380 h 335 h 366

„Đ y f / Notices